

In the Claims:

A listing of claims as now amended, including additions in underline and deletions in strikethrough, is provided below.

1. (Currently amended) A resin sealing mold assembly having an upper mold and a lower mold, comprising:

a substantially hexahedral cavity for housing at least a lead frame and a semiconductor element; and

at least one air releasing groove formed at contact surface of at least the said upper mold or the lower mold positioned at from at least one corner of the hexahedral cavity;

wherein a distance between the contact surface of the upper mold and the contact surface of the lower mold proximate the cavity at a vicinity of the cavity is about a thickness of the lead frame.

2. (Currently amended) The resin sealing mold assembly according to claim 1 , wherein first air vents and second air vents that are independent from each other are formed in a lead frame to be pressed by the upper mold and the lower mold at the corners , and the said first and second air vents are connected via the air releasing grooves.

3. (Currently amended) The resin sealing mold assembly according to claim 2 , wherein the said air releasing grooves are continuously formed from said cavity and positioned almost over or under said first air vent formed continuously from the cavity.

4. (Currently amended) The resin sealing mold assembly according to claim 2 , wherein the said cavity formed by the said upper mold and the said lower mold includes a part of the said first air vents.

5. (Currently amended) The resin sealing mold assembly according to claim 1 , wherein one end of each the said air releasing groove positioned at the a cavity side is formed at the said contact surfaces distant from proximate the said cavity region.
6. (Currently amended) The resin sealing mold assembly according to claim 21 , wherein first air vents and second air vents that are independent from each other are formed in the said lead frame to be pressed by the upper mold and the lower mold at a plurality of corners , and a resin injection gate is formed at least at one of the said corners , one end of the said resin injection gate positioned at the a cavity side is formed at the said contact surfaces distant from proximate the said cavity region, and the said one end of the resin injection gate and the first air vent are continued to each other.
7. (Cancelled).
8. (New) The resin sealing mold assembly according to claim 1, wherein said distance between the contact surface of the upper mold and the contact surface of the lower mold proximate the cavity at a vicinity of the cavity is essentially the same as a thickness of the lead frame.
9. (New) The resin sealing mold assembly according to claim 1, wherein said lead frame is approximately 100 to 250 μm .
11. (New) The resin sealing mold assembly according to claim 1, wherein said distance between the contact surface of the upper mold and the contact surface of the lower mold proximate the cavity at a vicinity of the cavity is open by a degree corresponding to the thickness of the lead frame.

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Applicant: Isao OCHIAI

12. (New) The resin sealing mold assembly according to claim 11, wherein said vicinity of the cavity is adjacent said cavity.